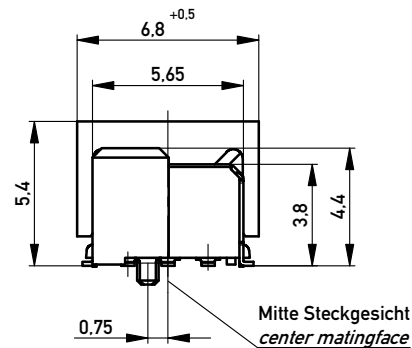
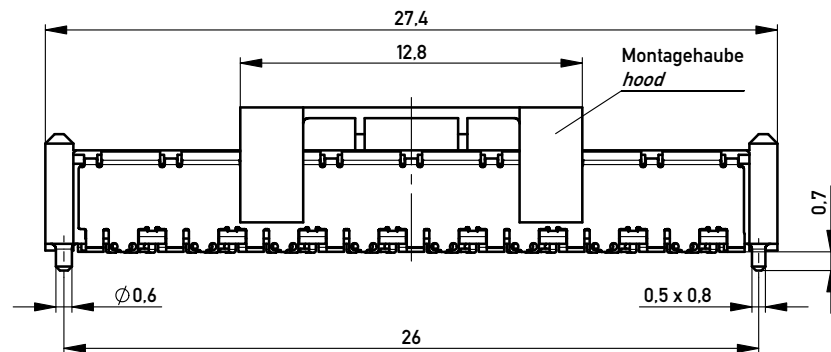
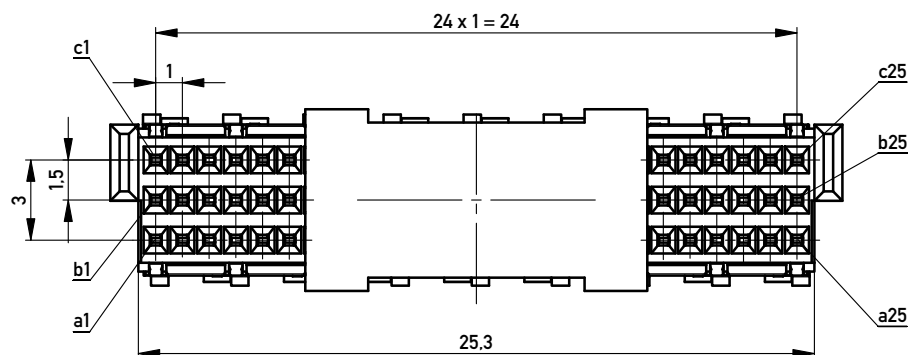
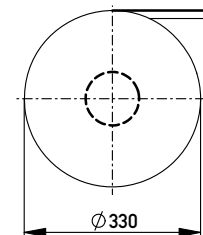
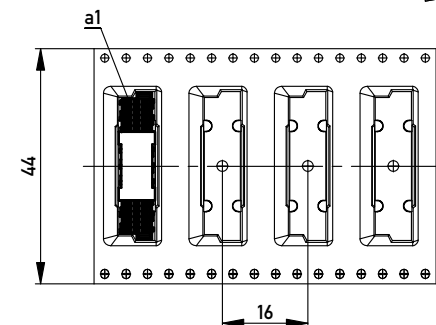




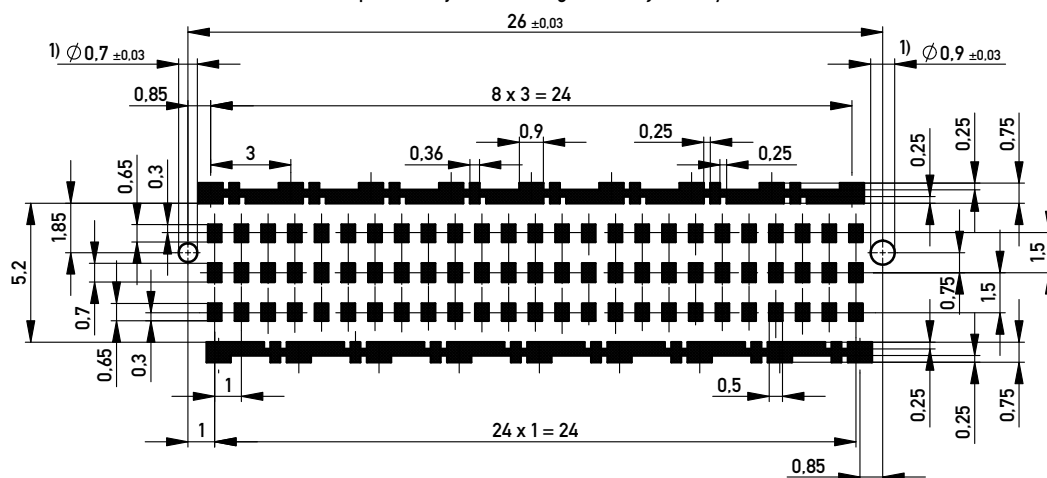
Verpackt im Reel in Anlehnung an DIN IEC 60286-3
Tape on Reel Packaging according to DIN IEC 60286-3
Verpackungseinheit: 550 Stück
Packaging unit: 550 pcs



Abspulrichtung - Reel off Direction



Leiterplatten-Layout Vorschlag / PCB-Layout Proposal



1) Durchmesser des Bohrers / Drill tool

Für weitere Layout Details bitte
Applikations Schrift MicroSpeed beachten.
For further layout details please
consider MicroSpeed application note.

Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

Anschlussbereich verzinkt 4-6 µm
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
Coplanarity Area of Termination ≤ 0,1 mm

MicroSpeed Triple

Information:		Tolerances		Scale	5:1
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b		15.04.2015		F04 SMD BM EMV 75 pol. F04 SMD BM EMV 75 pin	
Index		Date		474473	
				Class	
				MSPEED	

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